

APPARATUS AND METHODS OF FORMING WIRE BONDS

ABSTRACT OF THE DISCLOSURE

A wire bonding apparatus includes a processing block, a bond head assembly and an infrared radiation source for selectively heating the bond pad areas of one or more semiconductor dies and/or bonding sites on a substrate. Methods for forming wire bonds
5 using selective heating of the bond pad areas of one or more semiconductor dies and/or bonding sites on the substrate are also disclosed.

Figure 3A

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